

MAN Diag

INTRODUCTION

MLCC(Multilayer Ceramic Capacitor) is SMD(Surface Mounted Device) type capacitor that is used in wide ranges of capacitance. MLCC is paid more attentions than other capacitors due to the better frequency characteristics, higher reliability, higher withstanding voltage and so on.

MLCC is made of many layers of ceramic and inner electrodes like sandwich. Pd was used for inner electrodes. But the price of Pd was skyrocketed and Pd was replaced by the BME(Base Metal Electrode), which reduced the total cost of MLCC.

This inner electrode is connected to outer termination for surface mounting, which is composed of three layers, Cu or Ag layer, Ni plating layer, and SnPb or Sn plating layer. Most of MLCCs become Pb free by the environmental issue at present.

MLCC is divided into two classes. Class I(C0G, etc) is the temperature compensating type. It has a small TCC(Temperature Coefficient of Capacitance) and a better frequency performance. Therefore, it is used in RF applications such as cellular phone, tuner, and so on. Class II(X7R, X5R, Y5V, etc) is the high dielectric constant type, which is used in general electronic circuit. Especially high capacitance MLCC is replacing other capacitors (Tantalum and Aluminum capacitor) due to the low ESR(Equivalent Series Resistance) value.

■ FEATURE AND APPLICATION

Feature

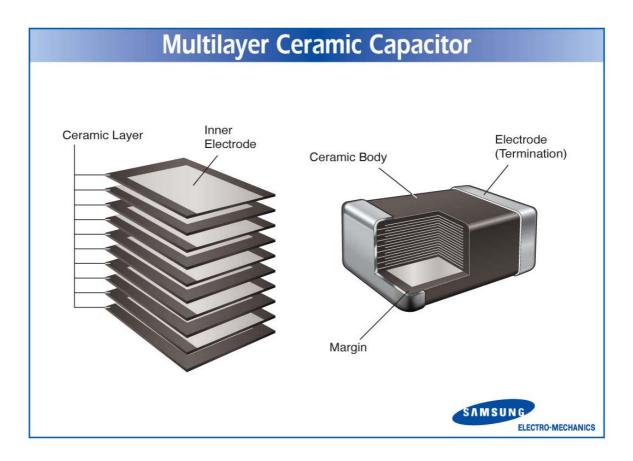
- Miniature Size
- Wide Capacitance and Voltage Range
- Highly Reliable Performance
- Tape & Reel for Surface Mount Assembly
- Low ESR
- High Q at High Frequencies
- Stable Temperature Dependence of Capacitance

Application

- High Frequency Circuit(Tuner, VCO, PAM etc)
- General Power Supply Circuit(SMPS etc)
- DC-DC Converter
- General Electronic Circuit

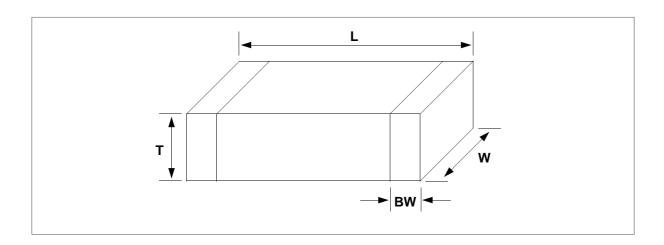


■ STRUCTURE





■ APPEARANCE AND DIMENSION



CODE	EIA CODE	DIMENSION (mm)						
CODE	LIA CODE	L	W	T (MAX)	BW			
03	0201	$0.6~\pm~0.03$	0.3 ± 0.03	$0.3~\pm~0.03$	0.15±0.05			
05	0402	1.0 ± 0.05	0.5 ± 0.05	0.5 ± 0.05	0.2+0.15/-0.1			
10	0603	1.6 ± 0.1	0.8 ± 0.1	0.8 ± 0.1	0.3 ± 0.2			
21	0805	2.0 ± 0.1	1.25 ± 0.1	1.25± 0.1	0.5+0.2/-0.3			
31	1206	3.2 ± 0.2	1.6 ± 0.2	1.6 ± 0.2	0.5+0.2/-0.3			
32	1210	3.2 ± 0.3	2.5 ± 0.2	2.5 ± 0.2	0.6 ± 0.3			
43	1812	4.5 ± 0.4	3.2 ± 0.3	3.2 ± 0.3	0.8 ± 0.3			
55	2220	5.7 ± 0.4	5.0 ± 0.4	3.2 ± 0.3	1.0 ± 0.3			



■ PREVIOUS PART NUMBERING

 CL
 10
 C
 101
 J
 B
 N
 C

 0
 2
 3
 4
 5
 6
 7
 3

- 1 SAMSUNG Multilayer Ceramic Capacitor
- 2 Type(Size)
- 3 Capacitance Temperature Characteristics
- 4 Nominal Capacitance
- **6** Capacitance Tolerance
- 6 Rated Voltage
- **7** Thickness Option
- 8 Packaging Type

3 CAPACITANCE TEMPERATURE CHARACTERISTICS

► CLASS I (Temperature Compensation)

Symbol	EIA Code	Temperature Coefficient(PPM/℃)	* Temperature Characteristics	Operation Temperature Range
С	C0G(CH)	0 ± 30	CΔ	
Р	P2H	-150 ± 60	РΔ	
R	R2H	-220 ± 60	R∆	
S	S2H	-330 ± 60	SΔ	-55 ~ +125℃
Т	T2H	-470 ± 60	TΔ	
U	U2J	-750 ± 120	UΔ	
L	S2L	+350 ~ -1000	SL	

***** Temperature Characteristics

Characteristics COG COG COG COG COG COG COG P2H P2H					
P Δ - P2J P2H P2H	•	below 2.0pF	2.2 ~ 3.9pF	above 4.0pF	above 10pF
	CΔ	C0G	C0G	C0G	C0G
PA PAL PAL PAL	РΔ	-	P2J	P2H	P2H
KA - KZJ KZH KZH	RΔ	-	R2J	R2H	R2H
S Δ - S2J S2H S2H	SΔ	-	S2J	S2H	S2H
T Δ - T2J T2H T2H	TΔ	-	T2J	T2H	T2H
U Δ - U2J U2J U2J	UΔ	-	U2J	U2J	U2J

☞ K : ±250 PPM/℃

J : ±120 PPM/℃ H : ±60 PPM/℃

G : ±30 PPM/℃

► CLASS II (High Dielectric Constant)

Symbol	EIA Code	Capacitance Change (ΔC : %)	Operation Temperature Range
Α	X5R	± 15	-55 ~ +85℃
В	X7R	± 15	-55 ~ +125℃
F	Y5V	+22 ~ -82	-30 ~ +85℃



4 NOMINAL CAPACITANCE

The nominal capacitance value is expressed in pico-Farad(pF) and identified by three-digit number, first two digits represent significant figures and last digit specifies the number of zeros to follow. For values below 1pF, the letter "R" is used as the decimal point and the last digit becomes significant.

example)

100 : 10 ×	10° =	10pF	
102 : 10 ×	$10^2 =$	1000pF	
020 : 2 ×	10° =	2pF	
1R5 : 1.5pF	•		

6 CAPACITANCE TOLERANCE

Temperature Characteristics	Symbol	Tolerance	Applicable Capacitance & Range
	В	± 0.1pF	0.5 ~ 3pF
	С	± 0.25pF	0.5 1055
C0G(NPO)	D	± 0.5pF	0.5 ~ 10pF
or	F	± 1pF	6 ~ 10pF
T.C Series	G	± 2%	
	J	± 5%	E-24 Series for over 10pF
	K	± 10%	
. ()(==)	J	± 5%	
A(X5R)	K	± 10%	E-12 Series
B(X7R)	М	± 20%	
F(Y5V)	Z	-20% ~ +80%	E-6 Series

^{*} Please consult us for special tolerances.

6 RATED VOLTAGE

Symbol	Rated Voltage(Vdc)	Symbol	Rated Voltage(Vdc)
Q	6.3V	D	200V
Р	10V	G	500V
0	16V	ı	1000V
Α	25V	J	2000V
В	50V	К	3000V
С	100V		



7 THICKNESS OPTION

Symbol	Description of the Code					
N	Standard thickness (please refer to standard thickness table on next page)					
Α	Thinner than standard thickness					
В	Thicker than standard thickness					
С	Standard Thickness High Q (Low ` D.F `)					
D	Sn-100% (High-Q)					
E	Sn-100% (General)					

^{*} Please Consult us for other termination type.

8 PACKAGING TYPE

Symbol	Packaging	Symbol	Packaging
В	Bulk	F	Embossed Tape, 13" Reel
Р	Cassette	L	Paper 13" Reel
С	Paper Tape, 7" Reel	0	Paper 10" Reel
D	Paper Tape, 13" Reel	S	Embossed Tape, 10" Reel
Е	Embossed Tape, 7" Reel		

▶ STANDARD CAPACITANCE STEP

Series		Capacitance Step										
E- 3		1	.0			2	.2			4	.7	_
E- 6	1	.0	1	.5	2	.2	3	.3	4	.7	6	.8
E-12	1.0	1.2	1.5	1.8	2.2	2.7	3.3	3.9	4.7	5.6	6.8	8.2
F 04	1.0	1.2	1.5	1.8	2.2	2.7	3.3	3.9	4.7	5.6	6.8	8.2
E-24	1.1	1.3	1.6	2.0	2.4	3.0	3.6	4.3	5.1	6.2	7.5	9.1

^{*} Standard Capacitance is " Each step ×10" "



■ NEW PART NUMBERING

 CL
 10
 C
 101
 J
 B
 8
 N
 N
 N
 C

 0
 2
 3
 4
 6
 6
 7
 8
 9
 0
 0

- 1 SAMSUNG Multilayer Ceramic Capacitor
- 2 Size(mm)
- 3 Capacitance Temperature Characteristic
- 4 Nominal Capacitance
- **6** Capacitance Tolerance
- 6 Rated Voltage
- **7** Thickness Option
- 8 Product & Plating Method
- Samsung Control Code
- 10 Reserved For Future Use
- 1 Packaging Type

1 PRODUCT ABBREVIATION

Symbol	Product Abbreviation
CL	SAMSUNG Multilayer Ceramic Capacitor

2 SIZE(mm)

Symbol	Size(mm)					
Symbol	Length	Width				
03	0.6	0.3				
05	1.0	0.5				
10	1.6	0.8				
21	2.0	1.2				
31	3.2	1.6				
32	3.2	2.5				
43	4.5	3.2				
55	5.7	5.0				



3 CAPACITANCE TEMPERATURE CHARACTERISTIC

Symbol		Temperature Range				
С		COG	C△	0±30(ppm/°C)		
P		P2H	P△	-150±60		
R		R2H	R△	-220±60		
S	Class	S2H	S2H S△ -330±60		-55 ~ +125℃	
Т		T2H	T△	-470±60		
U		U2J	U△	-750±60		
L		S2L	S△	+350 ~ -1000		
Α		X5R	X5R	±15%	-55 ~ +85℃	
В	Class II	X7R	X7R X7R ±15%		-55 ~ +125℃	
F		Y5V	Y5V	+22 ~ -82%	-30 ~ +85℃	

***** Temperature Characteristic

Temperature Characteristics	Below 2.0pF	Above 4.0pF	Above 10pF			
CΔ	C0G	C0G	C0G	C0G		
РΔ	-	P2J	P2H	P2H		
RΔ	-	R2J	R2H	R2H		
SΔ	-	S2J	S2H	S2H		
TΔ	ΤΔ -		T2H	T2H		
UΔ	-	U2J	U2J	U2J		

J : $\pm 120PPM/^{\circ}C$, H : $\pm 60PPM/^{\circ}C$, G : $\pm 30PPM/^{\circ}C$

4 NOMINAL CAPACITANCE

Nominal capacitance is identified by 3 digits.

The first and second digits identify the first and second significant figures of the capacitance. The third digit identifies the multiplier. 'R' identifies a decimal point.

Example

Symbol	Nominal Capacitance
1R5	1.5pF
103	10,000pF, 10nF, 0.01 μ F
104	100,000pF, 100nF, 0.1 µ F



6 CAPACITANCE TOLERANCE

Symbol	Tolerance	Nominal Capacitance
Α	±0.05pF	
В	±0.1pF	<u>.</u> <u>.</u>
С	±0.25pF	Less than 10pF (Including 10pF)
D	±0.5pF	(modding Topi)
F	±1pF	
F	±1%	
G	±2%	
J	±5%	Mars than 10pF
K	±10%	More than 10pF
М	±20%	
Z	+80, -20%	

6 RATED VOLTAGE

Symbol	Rated Voltage	Symbol	Rated Voltage
Q	6.3V	E	250V
Р	10V	G	500V
0	16V	Н	630V
Α	25V	ı	1,000V
В	50V	J	2,000V
С	100V	K	3,000V
D	200V		



7 THICKNESS OPTION

Туре	Symbol	Thickness(T)	Spec	
0603	3	0.30	±0.03	
1005	5	0.50	±0.05	
1608	8	0.80	±0.10	
	Α	0.65	10.40	
2012	С	0.85	±0.10	
	F	1.25	±0.10	
	С	0.85	±0.15	
3216	F	1.25	±0.15	
	Н	1.6	±0.20	
	F	1.25		
2225	Н	1.6	10.20	
3225	I	2.0	±0.20	
	J	2.5		
	F	1.25		
	Н	1.6	±0.20	
4532	I	2.0	±0.20	
	J	2.5		
	L	3.2	±0.30	
	F	1.25		
	Н			
5750	I	2.0	±0.20	
	J	2.5		
	L	3.2	±0.30	



19 PRODUCT & PLATING METHOD

Symbol	Electrode	Plating Type	
Α	Pd	Ag	Sn_100%
N	Ni	Cu	Sn_100%
G	Cu	Cu	Sn_100%

9 SAMSUNG CONTROL CODE

Symbol	Description of the code	Symbol	Description of the code
Α	Array (2-element)	N	Normal
В	Array (4-element)	Р	Automotive
С	High - Q	W	3 Terminal EMI Filter
L	LICC		

10 RESERVED FOR FUTURE USE

Symbol	Description of the code
N	Reserved for future use

1 PACKAGING TYPE

Symbol	Packaging Type	Symbol	Packaging Type
В	Bulk	F	Embossing 13" (10,000EA)
Р	Bulk Case	L	Paper 13" (15,000EA)
С	Paper 7"	0	Paper 10"
D	Paper 13" (10,000EA)	S	Embossing 10"
E	Embossing 7"		



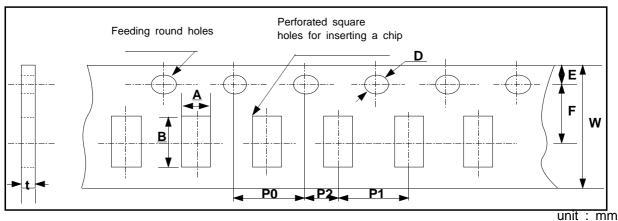
► CAPACITANCE vs CHIP THICKNESS STANDARD

De	scripti	on		1005 (0402)	1608 (0603)	20	12 Ty (0805	/pe)	32	:16 Ty (1206	/pe		3225 (1	5 Type 210)			4532 (1	2 Type 812)	•	57	750 T (2220	ype D)				
L		L	0.6 ±0.03	1.0 ±0.05	1.6 ±0.1		2.0±0.1	1	3.2±	3.2±0.15		3.2±0.15 3.2 ±0.2			3.2±0.3				4.5±0.4					5.7±0.4		
Dim (ı	ension nm)	w	0.3 ±0.03	0.5 ±0.05	0.8 ±0.1		1.25±0.	1	1.6±	0.15	1.6 ±0.2		2.5	5±0.2			3.2	2±0.3			5.0±0	.4				
		т	0.3 ±0.03	0.5~ ±0.05	0.8 ±0.1	0.65 ±0.1	0.85 ±0.1	1.25 ±0.1	0.85 ±0.15	1.25 ±0.15	1.6 ±0.2	1.25 ±0.2	1.6 ±0.2	2.0 ±0.2	2.5 ±0.2	1.25 ±0.2	1.6 ±0.2	2.0 ±0.2	2.5 ±0.2	1.6 ±0.2	2.0 ±0.2	2.5 ±0.2				
Ç	SL	50V	-	0.5~ 240	0.5 ~ 1000	0.5 ~1000	1100 ~ 1500	1600~ 2700	0.5 ~ 2700	3000~ 5600	6200~ 8200	-	-	-	-	-	-	-	-	-	-	-				
CAPACITANCE RANGE (PF)	С. ТС	25V	0.5~ 47	0.5~ 220	0.5 ~ 1000	-	-	3300~ 8200	1500~ 3600	3900~ 6800	7500~ 10000	-	-	-	-	-	100000	-	-	-	-	-				
(PF)	C, TC (Except SL,UJ)	50V	-	0.5 ~ 180	0.5 ~ 1000	0.5 ~ 560	620~ 1000	1100~ 3300	0.5 ~ 2200	2400~ 4700	-	560~ 10000	11000 22000	47000	-	1000~ 13000	15000~ 22000	24000~ 47000	62000~ 68000	43000	93000	130000				
		6.3V	10	220	2200	-	-	10000	-	-	10000	-	-	-	22000	-	-	-	47000	-	-	47000				
		10V	10	100	1000	-	-	2200	-	-	4700~ 10000	-	-	-	22000	-	-	-	-	-	-	47000				
	A (X5R)	16V	-	47	330~ 470	-	-	1000	-	-	4700	-	-	-	6800~ 10000	-	-	-	-	-	-	-				
		25V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-				
		50V	ı	6.8~ 10	-	1	'	-	-	-	1	-	-	-	-	1	-	-	-	-	-	1				
C A P		6.3V	0.1~ 10	47~ 100	470~ 1000	-	-	1000	-	-	6800~ 10000	-	-	-	22000	-	-	-	-	-	-	-				
CAPACITANCE		10V	0.1~ 10	33~ 100	220~ 470	220~ 270	330~ 470	560~ 1000	-	1000~ 3300	4700	1500~ 2200	3300	3900~ 4700	-	-	-	-	22000	-	-	-				
	B (X7R)	16V	0.1~ 1	10~ 33	100~ 220	68~ 200	220~ 330	390~ 1000	330~ 680	1000~ 1500	2200~ 3300	1500~ 2200	3300	3900~ 4700	-	-	-	2200	-	-	-	-				
R A N G E		25V	-	4.7~ 10	47~ 100	39~ 68	82~ 100	150~ 470	100~ 330	470~ 620	680~ 1000	680~ 1500	1800	2200	-	-	-	1000	-	-	-	10000				
E (nF		50V	-	0.22~ 4.7	0.22~ 100	0.22~ 39	47~ 100	220	1~ 150	220	390~ 1000	2.2~ 680	820~ 1000	-	-	10~ 1000	-	-	-	-	-	3300~ 4700				
٠		6.3V	10~ 100	-	2200	-	-	10000	-	-	•	-	-	47000	-	-	-	-	-	-	-	-				
		10V	-	220~ 330	100~ 1000	-	-	4700	-	4700	10000~ 22000	-	-	-	22000	-	-	-	-	-	-	100000				
	F (Y5V)	16V	-	10~ 220	100~ 1000	10~ 680	820~ 1000	1200~ 2200	1000~ 2200	2700~ 4700	10000	3300~ 6800	10000	15000	-	-	-	22000	-	-	-	-				
		25V	-	10~ 33	22~ 330	10~ 220	270~ 470	560~ 1000	470~ 1000	1200~ 2200	2700~ 3300		4700~ 10000	-	-	-	-	-	10000	-	-	-				
		50V	-	2.2~ 10	2.2~ 100	2.2~ 68	82~ 150	180~ 1000	10~ 470	560~ 1000	-	100~ 1000	-	-	-	-	-	-	10000	-	-	-				



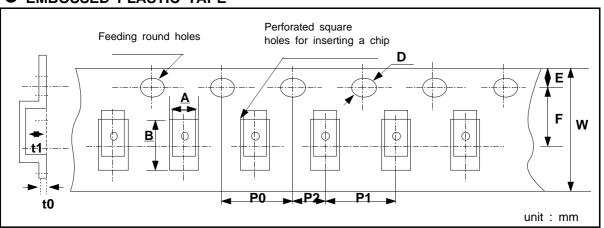
■ PACKAGING

CARDBOARD PAPER TAPE



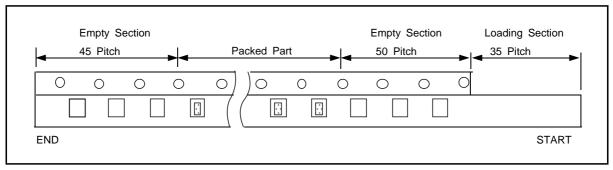
Symbol Type		w	F	E	P1	P2	P0	D	t	A	В
	03				2.0			Ф1.5 +0.1/-0	0.37 ±0.03	0.38 ±0.03	0.68 ±0.03
D i m	05				±0.05				0.6 ±0.05	0.65 +0.05/-0.1	1.15 +0.05/-0.1
e n s	10	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1		2.0 ±0.05	4.0 ±0.1			1.1 ±0.2	1.9 ±0.2
i o n	21				4.0 ±0.1				1.1 MAX	1.6 ±0.2	2.4 ±0.2
	31									2.0 ±0.2	3.6 ±0.2

EMBOSSED PLASTIC TAPE



	mbol ype	W	F	E	P1	P2	P0	D	t0	t1	Α	В
P.	21										1.45 ±0.2	2.3 ±0.2
n e	31										2.0 ±0.2	3.6 ±0.2
n s i	32	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.05	4.0 ±0.1	Ф1.5 +0.1/-0	0.6 max	2.5 max	2.9 ±0.2	3.6 ±0.2
o n	43										3.6 ±0.2	4.9 ±0.2
	55										5.4 ±0.2	6.0 ±0.2

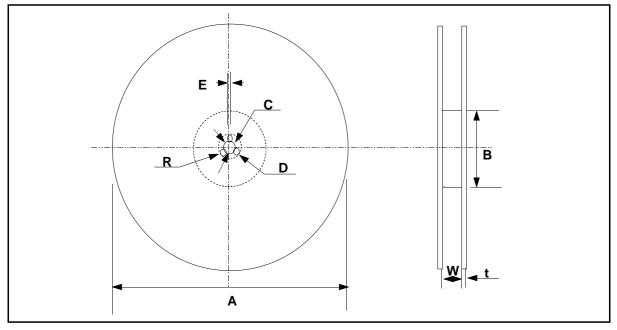
TAPING SIZE



unit: pcs

Symbol	Cardboard Paper Tape	Embossed Plastic Tape
7" Reel	4000	2000
13" Reel	15000	-

• REEL DIMENSION



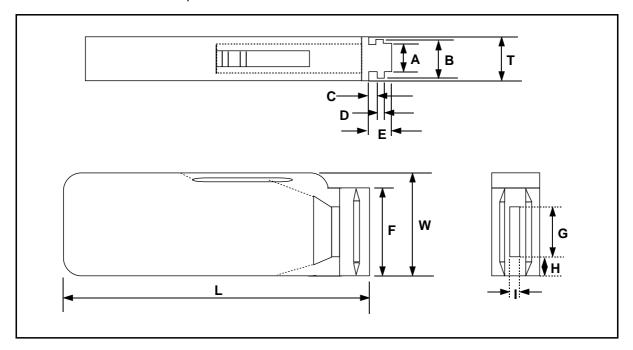
unit: mm

Symbol	Α	В	С	D	E	W	t	R
7" Reel	φ178±2.0	min.¢50						
13"	φ330±2.0	min.¢70	φ13±0.5	21±0.8	2.0±0.5	10±1.5	0.8±0.2	1.0
Reel	Ψ330±2.0	ππι.ψτυ						



BULK CASE PACKAGING

- Bulk case packaging can reduce the stock space and transportation costs.
- The bulk feeding system can increase the productivity.
- It can eliminate the components loss.



Symbol	Α	В	T	С	D	E
Dimension	6.8±0.1	8.8±0.1	12±0.1	1.5+0.1/-0	2+0/-0.1	4.7±0.1
Symbol	F	W	G	н	L	I

QUANTITY

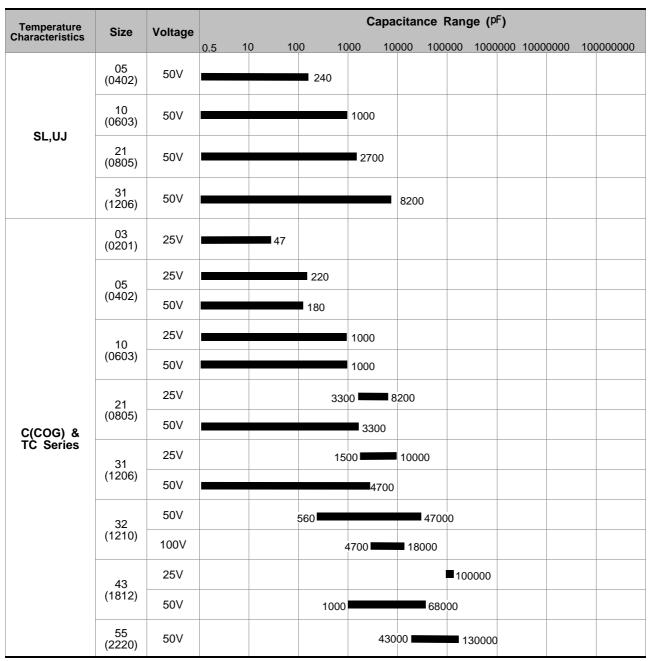
Size	05(0402)	10/0602\	21(0805)			
Size	05(0402)	10(0603)	T≤0.85mm	T≥1.0mm		
Quantity	50,000	10,000~15,000*	10,000	5,000		

^{*} Option



■ CHARACTERISTIC MAP

• CLASS I





lacktriangle CLASS II , A(X5R)

Temperature Characteristics	Size	Voltage				Capacita	nce Ran	ge (pF)			
Characteristics	O12C	Voltage	10	10	0 10	00 100	00 100	000 100	0000 100	00000 10	0000000
	0603	6.3V					= 10000	1			
	(0201)	10V					1 0000				
		6.3V						22000	0		
	1005	10V						1 00000			
	(0402)	16V					4 700	00			
_		50V				6800■	10000				
		6.3V							= 22000	00	
	1608 (0603)	10V							1 00000	0	
	(3333)	16V					330	000 ■ 470	000		
		6.3V								1 00000	00
A(X5R)	2012 (0805)	10V							22000	00	
	(0000)	16V							1 00000	0	
		6.3V								1 00000	00
	3216 (1206)	10V						4700	000	10000000)
	(1200)	16V							470 0	0000	
		6.3V								220000	00
	3225 (1210)	10V								220000	00
	()	16V						680	0000	10000000)
	4532 (1812)	6.3V								470 0	00000
		6.3V								4700	00000
	5750 (2220)	10V								4 700	00000



lacktriangle CLASS II , B(X7R)

Temperature	C:	Valtana			Сара	acita	nce Ran	ge (pF)			
Temperature Characteristics	Size	Voltage	10	100	1000	100	000 100	000 100	0000 100	00000 1	00000000
		6.3V		100			10000				
	03 (0201)	10V		100			10000				
		16V		100	1000	0					
		6.3V				47	000	100000			
		10V				330	000	100000			
	05 (0402)	16V			1	0000	33000)			
	(0402)	25V			4700 I		10000				
		50V		220■		4700					
		6.3V					47	70000	1000000)	
		10V					2200	00 🚾 470	000		
	10 (0603)	16V					100000	220000)		
B(X7R)	(====,	25V				47	′000 ——	100000			
		50V		220				100000			
		6.3V							1 0000	00	
		10V					22000	00	1000000)	
	21 (0805)	16V					68000		1000000)	
		25V				39	000	4700	000		
		50V		220 ■				220000			
		6.3V						680	00000	100000	00
		10V						1000000	470	0000	
	31 (1206)	16V					3300	000	33000	000	
		25V					100000		1000000)	
		50V			1000				1000000		



lacktriangle CLASS II , B(X7R)

Temperature	Size	Voltage				Capacita	nce Ra	nge (PF)			
Characteristics	O.Z.O	Voltage	10	10	0 10	00 100	000 1	00000 100	0000 1000	00000 10	0000000
		6.3V								220000	00
		10V						150000	0 470	0000	
	32 (1210)	16V						150000	0 470	0000	
		25V						680000	220000	0	
		50V			220	0			1000000		
B(X7R)		10V								2 20000	00
	43	16V							220000	00	
	(1812)	25V							■ 100000	0	
		50V				10000			1000000		
	55	25V								1 00000	000
	(2220)	50V						33000	00 🕶 470	0000	



Multilayer Ceramic Capacitor ● class II , F(Y5V)

Temperature Characteristics	Size	Voltage					Capa	citance F	Range (P	F)		
Characteristics		ronago	10	•	100	1000	100	000 100	0000 100	0000 1000	00000 1	00000000
	03 (0201)	6.3V					10000		100000			
		10 V						220000	33000	00		
	05	16 V					10000		220000			
	(0402)	25 V					10000	33000)			
		50 V			2	2200 ■		10000				
		6.3V								= 22000	00	
		10 V						100000		1000000		
	10 (0603)	16 V						100000		1000000		
	, ,	25 V					2200	0	330000			
		50 V			2	2200 ■			100000			
		6.3V									1 0000	000
		10 V								470	0000	
	21 (0805)	16 V					10000			220000		
	(0003)	25 V					10000			1000000		
F(Y5V)		50 V				2200 ■				1000000		
		10 V									22000	000
		16 V										
	31 (1206)	25 V						470		33000		
		50 V					10000			1000000	,00	
		6.3V					10000			1000000	1 470	000000
		10 V										
	32	16 V							22000	200	2200	
	(1210)	25 V							1000000		150000	
								100000	1000000		1000000	,0
		50 V						100000		1000000	- 0000	
	43	16V									2200	
	(1812)	25 V									10000	
	55	50 V									1 0000	
	(2220)	10 V										1 00000

■ RELIABILITY TEST DATA

NO	ITE	М	PERFORMANCE						TE	ST CONDITION	
1	APPEAR	RANCE	NC	O ABNORM	IAL EXTERIOR	APPEARANCE		THROUGH MIC	ROSC	OPE(×10)	
2	INSULA RESIST		SN (R	MALLER ATED VOL	$500 ext{M}\Omega \cdot \mu ext{F} ext{ PROD}$ TAGE IS BELOV	NUCT WHICHEVE	R IS	RATED VOLTAGE SHALL BE APPLIED. MEASUREMENT TIME IS 60 ~ 120 RATED VOLTAGE TIME 60 SEC.			
3	WITHST <i>I</i>				RIC BREAKDOV BREAKDOWN	VN OR		CLASS II :250% (OF THE	E RATED VOLTAGE RATED VOLTAGE SS THAN 50 MA CUR	FOR 1~5 SEC
								CAPACITAN	CE	FREQUENCY	VOLTAGE
		CLASS		WITHIN TOLERA	THE SPECIFIED			1,000 pF AN	D	1账±10%	0.5 ~ 5 Vrms
4	CAPACIT	1		TOLLIVA	NOL			MORE THA 1,000pF	N	1㎞±10%	0.5 ~ 5 VIIIS
	ANCE							CAPACITAN	CE	FREQUENCY	VOLTAGE
		CLASS		WITHIN	THE SPECIFIED			10μF AND BEL	_OW	1kHz±10%	1.0±0.2Vrms
		П		TOLERA	NCE			MORE THAN 10μΓ		120Hz±20%	0.5±0.1Vrms
								CAPACITAN	CE	FREQUENCY	VOLTAGE
5	Q	CLASS I			Q ≥1,000 30pF: Q ≥400 +	-20C		1,000 pF AN BELOW	D	1账±10%	0.5 ~ 5 Vrms
		1			(C : CAPACI	TANCE)		MORE THAN 1,000pF		1kHz±10%	0.5 ~ 5 VIIIIS
			1.	CHAR : E	3			CAPACITAN	CAPACITANCE FREQUENCY		
				RATE	VOLTAGE	DF SPEC		10μF AND BEL	_OW	1kHz±10%	1.0±0.2Vrms
					6.3V	0.05 max		MORE THAN	10 μF	120Hz±20%	0.5±0.1Vrms
					10V	0.05 max					
					16V	0.035 max					
			-		25V	0.025 max					
				50	V 이상	0.025 max					
			2.	CHAR : F	:						
	T 8	CLASS			6.3V	10V		16V		25V	50V
6	Tanδ	П		1005	-	0.125max		ax (C < 220nF)		0.05max	0.05max
				1608	0.16max	0.125max		0.09max	ax (C≥220nF) 0.05n 0.09max		0.05max
				2012	0.16max	0.125max		0.09max	0.0	7max(C>100nF) 0.07max	0.05max
			3216 0.16max		0.125max		0.09max		0.07max	0.05max	
		3225 0.16max		0.125max		0.09max		7max(C≤6.8μF) 9max(C>6.8μF)	0.05max		
			4532 0.16max 0.16max				0.09max		-	-	
				5750 0.125max							



NO	ITE	M	PERF	ORMANCE	TEST CONDITION				
	712		, EIG		THESE SYMMETRICAL TOLERANCE APPLY TO				
			CHARACTERISTIC	TEMP. COEFFICIENT	2 POINT MEASUREMENT OF TEMPERATURE				
			000	(PPM/℃)	COEFFICIENT: ONE AT 25℃ AND AT 85℃				
			C0G PH	0 ± 30 -150 ± 60	STEP TEMPERATURE				
7	CAPACITANCE	CLASS	RH	-220 ± 60	1 25 ± 2				
'	TEMPERATURE COEFFICIENT	I	SH	-330 ± 60	2 MIN RATED TEMP ± 2				
	OCETTIONENT		TH	-470 ± 60	3 25 ± 2				
			UL	-750 ± 120	4 MAX RATED TEMP ± 2				
			SL +350 ~ -1000		5 25 ± 2				
8	TEMPERATURE CHARACTERISTIC S	CLASS II	CAPACITANCE CHAR. A,B F	CHANGE CAP. CHANGE(%) ±15% +22% ~ -82%	The change of capacitance should be got from the capacitance at $25^{\circ}\mathbb{C}$. After capacitance measured from Min. Temp. to Max. Temp., it should be calculated from the formula below. $\frac{\text{C2 - C1}}{\text{C1}} \times 100\%$ $\text{C1 : CAPACITANCE AT STANDARD}$ $\text{TEMPERATURE}(25^{\circ}\mathbb{C})$ $\text{C2 : CAPACITANCE AT EACH}$ TEMPERATURE				
9	ADHESIVE S OF TERM		NO INDICATION OCCUR ON THE ELECTRODE.	OF PEELING SHALL TERMINAL	A 500g.f PRESSURE SHALL BE APPLIED FOR 10±1 SECOND. 500g.f SEE (FIG.1)				
		APPEARANCE	NO MECHANICA	L DAMAGE SHALL	BENDING SHALL BE APPLIED TO THE LIMIT(1mm) WITH 0.3mm/SEC.				
			CHARACTE	CHANGE OF CAPACITANCE	KEEP THE TEST BOARD AT THE LIMIT POINT IN 5 SEC., THEN MEASURE CAPACITANCE.				
10	BENDING STRENGTH		CLASS I	WITHIN $\pm 5\%$ OR \pm 0.5 pF WHICHEVER IS LARGER	CHARACTER LIMIT C, A, B, F 1mm 20 R=340				
		CAPACITANCE	CLASS II	F WITHIN ±12.5% WITHIN ±30%	50 BENDING				
					45±1 45±1 LIMIT SEE (FIG.2)				

NO	ITE	EM		PERF	ORMANCE		TEST C	ONDITION		
			MORE THA		OF THE TERMINAL	SOLDER	TEMPERATUR			
			SURFACE I	ѕ то в	E SOLDERED NEWLY,	DIP TIME	: 3±1 Sec			
			SO METAL	PART I	DOES NOT COME	SOLDER	: H63A			
			OUT OR D	SSOLVE	≣	FLUX	: RMA TYPE			
			/			*PB-FREE				
11	SOLDER	ABILITY	─ ►/		/ //-	SOLDER TEMPERATURE : $260\pm5^{\circ}$				
							: Sn96.5-3Ag-0	.5Cu		
			IN DD EDE		MODE THAN 050/		MA TYPE			
					, MORE THAN 95% L SURFACE IS TO BE		E: 3±0.1Sec	2 400°C FOD	10 00050	
			SOLDERED			PRE-HI	EATING : AT 80	J~120 C FOR	10~30SEC.	
					ICAL DAMAGE	DIP · SO	LDER TEMPER	ATURE OF		
		APPEARANCE		L OCCL			0±5℃	THORE OF		
			CHARACTE	RISTIC	CAP. CHANGE	DIP TIME	:10±1 SEC.			
					WITHIN ±2.5% OR	EACH TE	ERMINATION SI	HALL BE FULL	Υ	
			CLASS	I	±0.25 pF WHICHEVER	IMMERSE	ED AND PREHE	EATED		
		CAPACITANCE	IS LARGER			AS FOLL	OWING:			
			OL 400 II	A,B	WITHIN ±7.5%			TIME		
40	RESISTANCE		CLASSII	F	WITHIN ±20%	STEP	TEMP.(℃)	(SEC.)		
12	TO SOLDERING HEAT	Q	30pF AND 0	OVER :	Q≥ 1000	1	80~100	60		
	TIE/(I	CLASS I	LESS THAN	1 30 pF	: Q≥ 400+20×C	2	150~180	60		
		Tanδ	TO SATISF	Y THE	SPECIFIED	MEASUR	E AT ROOM T	EMP. AFTER	'	
		CLASS II	INITIAL VAL	LUE		COOLING	FOR			
		INSULATION	TO SATISF	Y THE	SPECIFIED	CLASS I : 24 ± 2 HOURS				
		RESISTANCE	INITIAL VAL	LUE		CLASSⅡ : 48 ± 4 HOURS				
		WITHSTANDING	TO SATISF		SPECIFIED					
		VOLTAGE	INITIAL VAL							
		APPEARANCE		NICAL I	DAMAGE SHALL		SHALL BE AF			
			OCCUR.	DISTIC	CAP. CHANGE		IT(1mm) WITH IE TEST BOAR		IIT POINT	
			CHARACTE	KISTIC			C., THEN MEAS			
					WITHIN ±2.5% OR ±0.25pF					
		CAPACITANCE	CLASS	Ι	WHICHEVER	CHAR		ICY RANGE		
					IS LARGER	A,B,C,	F 10Hz → 55	5Hz → 10Hz		
			CLASS	A,B	WITHIN ±5%	CHAR	. TRAVER	SED TIME		
13	VIBRATION		П	F	WITHIN ±20%	A,B,C,	F 1	min		
13	TEST	Q	30pF AND 0	OVER :	Q≥ 1000	THE ENT	IRE FREQUEN	CY RANGE.		
		CLASS I	LESS THAN	1 30pF :	$Q{}^{\geq}~400{+}20{\times}C$			•		
		Tanδ	TO SATISE	Y THE	SPECIFIED	FROM 10 TO 55Hz AND RETURN TO 10Hz, SHALL BE TRAVERSED				
		CLASS II	INITIAL VA	LUE		IN 1 MIN	UTE.			
		INSULATION	TO SATISE	Y THE	SPECIFIED		CLE SHALL BE			
		RESISTANCE	TO SATISFY THE SPECIFIED INITIAL VALUE			2 HOURS IN EACH THERE MUTUALLY				
						PERPENDICULAR DIRECTION,				
						FOR TOTAL PERIOD OF 6 HOURS.				

^{*} THE INITIAL VALUE OF HIGH DIELECTRIC CONSTANT SERIES SHALL BE MEASURED AFTER THE HEAT TREATMENT OF 150 +0/-10 $^{\circ}$ C, 1Hr and sitting of 48 $^{\pm}$ 4hr at room temperature & room humidity.



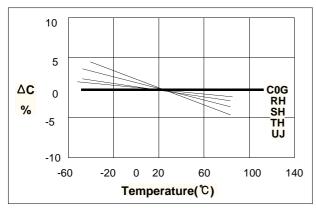
NO		ГЕМ	PERFORMANCE					т	EST CONDITION			
NO	•		NO MECHANICAL DAMAGE SHALL OCCUR					TEMPERAT				
		APPEARANCE							RELATIVE HUMIDITY:90~95 %RH			
			CHARAC	TERISTI			E CHAN	IGE		: 500 +12/-0 Hr.		
						WITHIN ±5% OR			1201 TIME 1 300 +127-0 TII.			
		CAPACITANCE	CLAS	SS I	-	WHICH	EVER		MEASURE AT ROOM TEMPERATURE			
						IS LARGER			AFTER COOLING FOR			
			CLASS	A,B		WITHIN ±12.5%			CLASS I : 24±2 Hr.			
				II F WITHIN ±30					CLASSⅡ : 48±4 Hr.			
		Q		_	: Q≥ 350							
	HUMIDITY	CLASS I	10 ~30pF		≥ 275 + 2. : Q≥ 200				6.3V	0.125 MAX *Condition		
14	(STEADY		LESS IT	AN TOPF	· . Q= 200	+ 10^(, 		Tanδ	4005 O > 0 00 F		
	STATE)		CHAR.	25V AND	16V	10V	6.3V	4V		1005 C ≥0.22μF 1608 C ≥2.2μF		
				OVER						2012 C ≥4.7μF		
		Tanδ	A,B	0.05	0.05 MAX	0.05 MAX	0.075 MAX	0.1 MAX	CLASS II	3216 C ≥10.0μF		
		CLASS II			0.1MAX				(A,B)	3225 C ≥22.0 <i>μ</i> F		
			F	0.075 MAX	(C ≦1.0µF) 0.125	0.15 MAX	0.195 MAX	0.25 MAX		4532 C ≥47.0 <i>μ</i> F		
				Wilde	MAX (C≥1.0 <i>μ</i> F)	140.00	140.00	W OC		5750 C ≥100.0µF		
			MINIMUM	INSULA	TION RES	ISTANCI	<u> </u>					
		INSULATION	1,000 MΩ	OR 50M	Ω·μF PRODU	JCT WH						
		RESISTANCE	SMALLER	2								
		APPEARANCE	NO MECH	HANICAL	DAMAGE	SHALL	APPLIED VOL	TAGE :				
									RATED VOLTAGE			
			CHARAC	TERISTI	C CAPAC	ITANCE	CHANG	3E	TEMPERATUR			
					WITHIN	√ ±7.5%	OR		RELATIVE HUMIDITY:90~95%RH TEST TIME: 500 +12/-0 Hr.			
			CLAS	SS I	±0.75	±0.75pF WHICHEVER				CURRENT APPLIED : 50mA MAX.		
				1	IS LAR	GER			<initial mea<="" td=""><td>ASUREMENT></td></initial>	ASUREMENT>		
				A,B WITHIN ±12.5%			CLASS II SHOULD BE MEASURED					
					WITHIN	WITHIN ±30%				FOR 1 HR IN 150°C+0/-10°C AND BE LEFT		
		CAPACITANCE			WITHIN	N +30~=	40%			AT ROOM TEMPERATURE.		
			CLASS			1005 C>0.47µF 1608 C>1.0µF				ASUREMENT>		
			П	F	1608 C					OULD BE MEASURED AFTER		
					2012 (շ>4.7µF				1±2 HRS IN ROOM		
4.5	MOISTURE				3216 0	Շ>10.0μϜ	=			RE AND HUMIDITY. HOULD BE MEASURED		
15	RESISTANCE					C>22.0µF				UE AFTER BE		
					4532 C	C>47.0µF	-			ED FOR 1 HR IN 150℃+0/-10		
		Q	-		: Q≥ 200				℃ AND BE L	EFT FOR 48±4HR AT ROOM		
		CLASS I	30pF AND	BELOV	V : Q≥ 100) + 10/	3×C		TEMPERATUR	RE.		
			CHAR.	25V AND	16V	10V	6.3V	4V	6.3V Tanδ	0.125 MAX *Condition		
				OVER						1005 C ≥0.22 <i>µ</i> F		
		Tanδ CLASS II	A,B	0.05 MAX	0.05 MAX	0.05 MAX	0.075 MAX	0.1 MAX		1608 C ≥2.2μF		
				IVIAX		IVIAX	IVIAX	IVIAX	CLASSII	2012 C ≥4.7μF 3216 C ≥10.0μF		
			F	0.075	0.1MAX (C <1.0μF)	0.15	0.195	0.25	(A,B)	3210 C ≥ 10.0 µF		
				F MAX 0.125MAX MAX MAX MAX (C≥1.0μF)					4532 C ≥47.0μF			
			MINIMUM	INSULA	TION RES	ISTANCI	 ≣:		 	5750 C ≥100.0μF		
		INSULATION	500 MΩ O	R 25MΩ·μ	∉F PRODUC	ΣT,						
		RESISTANCE	WHICHEV	ER IS	SMALLER.							

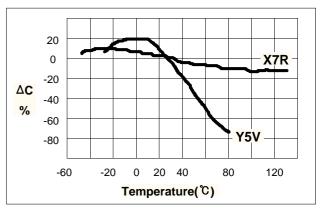
NO	ITE	EM .			PERFORM	ANCE			TEST CONDITION				
		APPEARANCE	NO MECH	HANICAI	L DAMAGE	E SHALI	L OCCL	JR	APPLIED VOLTAGE: 150%, 200% OF RATED VOLTAGE TEST TIME: 1000 +48/-0 Hr. CURRENT APPLIED: 50mA MAX. CHAR. TEMP.				
									CL	ASS I	125 ±3 ℃		
			CHARAC	IERISTI		CAP. CHANGE				А	85 ±3 ℃		
			CLAS	SS I		WITHIN ±3% OR ±0.3pF, WHICHEVER IS LARGER				S B	125 ±3 ℃ 85 ±3 ℃		
				A,B	WITHI	N ±12.	5%						
					WITHI	N ±30%	6			<initial measurement=""> CLASS Ⅱ SHOULD BE MEASURED INITIAL</initial>			
16	HIGH	CAPACITANCE	CLASS II	F	1005 (1608 (2012 (3216 (WITHIN+30~40% 1005 C>0.47μF 1608 C>1.0μF 2012 C>4.7μF 3216 C>10.0μF 3225 C>22.0μF				VALUE AFTER BE HEAT-TREATED FOR 1 HR IN 150°C+0/-10°C AND BE LEFT FOR 48± 4HR AT ROOM TEMPERATURE. <latter measurement=""> CLASS I SHOULD BE MEASURED AFTER LEFT FOR 24±2 HRS IN ROOM TEMPERATURE AND HUMIDITY.</latter>			
10	TEMPERATURE RESISTANCE					- C>47.0ր					MEASURED LATTER		
		Q CLASS I	30pF AND OVER : Q ≥ 350 $10 \sim 30 \text{pF}$: Q $\geq 275 + 2.5 \times \text{C}$ LESS THAN 10pF : Q $\geq 200 + 10 \times \text{C}$						VALUE AFTER BE HEAT-TREATED FOR 1 HR IN 150°C+0/-10°C AND BE LEFT FOR 4 4HR AT ROOM TEMPERATURE.				
				25V							orization Conditions		
			CHAR.	AND OVER	16V	10V	6.3V	4V			05 C>0.47μF 08 C ≥2.2 <i>μ</i> F		
		Tanδ CLASS II	A,B	0.05 MAX	0.05 MAX	0.05 MAX	0.075 MAX	0.1 MAX	CLASS I	I	12 C ≥4.7μF 16 C ≥10.0μF		
			F	0.075 MAX	0.1MAX (C<1.0μF) 0.125MAX (C≥1.0μF)	0.15 MAX	0.195 MAX	0.25 MAX	(,,=,,,,	453	25 C ≥22.0µF 32 C ≥47.0µF 50 C ≥100.0µF		
		INSULATION RESISTANCE	1,000 MΩ	OR 50M	ATION RES Ω·μF PROD SMALLER		CE:		APPLIED	TO ALL SERIE /ER, A/B는100	TAGE WILL BE S BUT ABOVE) 15 C ≥0.22µF		
		APPEARANCE	NO MECH	HANICAI	L DAMAGE	SHAL	L OCCL	JR			BE SUBJECTED		
			CHARAC	TERISTI	IC	CAP.	CHANG	E		CYCLES OF	THE E AS FOLLOWING		
					WITHI	N ±2.5	%		STEP				
		CAPACITANCE	CLAS	SS I	OR ±	-	WHICHE	EVER IS	1	TEMP.(℃) MIN.RATE	30		
	TEMPERATURE		CLASS	A,B		N ±7.5			2	TEMP.+0/-3	2~3		
17	CYCLE	Q	30 pF AN	F D OVER	WITHI	N ±20% 1000	6		3	MAX.RATE)		
		CLASS I	-		:Q ≥400 ·				3	TEMP.+3/-0	30		
		Tanδ	TO SATIS	SFY THE	E SPECIFI	ED			4	25	2~3		
		CLASS II	INITIAL V	ALUE					MEASUR	E AT ROOM	TEMPERATURE		
		INSULATION	TO SATIS	SFY THE	E SPECIFI	ED				OOLING FOR	!		
		RESISTANCE	INITIAL V		· · ·					: 24±2 Hr. : 48±4 Hr.			
									CLASS II	. 40±4 ∏.			

■ CHARACTERISTIC GRAPH

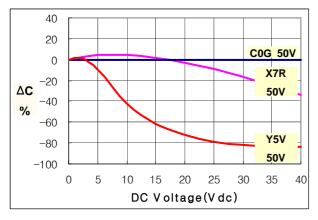
ELECTRICAL CHARACTERISTICS

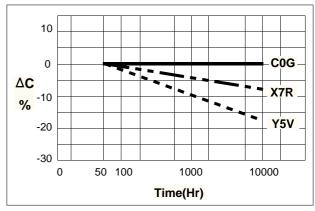
▶ CAPACITANCE - TEMPERATURE CHARACTERISTICS



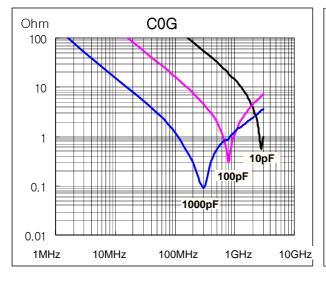


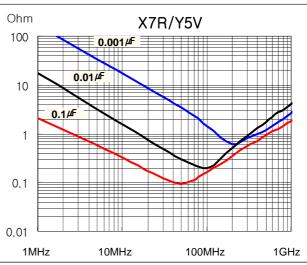
► CAPACITANCE - DC VOLTAGE CHARACTERISTICS ► CAPACITANCE CHANGE - AGING





▶ IMPEDANCE - FREQUENCY CHARACTERISTICS





APPLICATION MANUAL

Storage Condition

▶ Storage Environment

The electrical characteristics of MLCCs were degraded by the environment of high temperature or humidity. Therefore, the MLCCs shall be stored in the ambient temperature and the relative humidity of less than 40° C and 70%, respectively. Guaranteed storage period is within 6 months from the outgoing date of delivery.

Corrosive Gases

Since the solderability of the end termination in MLCC was degraded by a chemical atmosphere such as chlorine, acid or sulfide gases, MLCCs must be avoid from these gases.

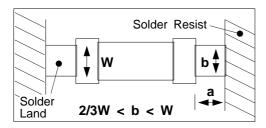
► Temperature Fluctuations

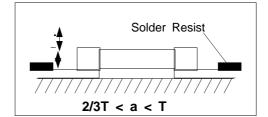
Since dew condensation may occur by the differences in temperature when the MLCCs are taken out of storage, it is important to maintain the temperature-controlled environment.

Design of Land Pattern

When designing printed circuit boards, the shape and size of the lands must allow for the proper amount of solder on the capacitor. The amount of solder at the end terminations has a direct effect on the crack. The crack in MLCC will be easily occurred by the tensile stress which was due to too much amount of solder. In contrast, if too little solder is applied, the termination strength will be insufficiently. Use the following illustrations as guidelines for proper land design.

Recommendation of Land Shape and Size





Adhesives

When flow soldering the MLCCs, apply the adhesive in accordance with the following conditions.

► Requirements for Adhesives

They must have enough adhesion, so that, the chips will not fall off or move during the handling of the circuit board.

They must maintain their adhesive strength when exposed to soldering temperature.

They should not spread or run when applied to the circuit board.

They should harden quickly.

They should not corrode the circuit board or chip material.



They should be a good insulator.

They should be non-toxic, and not produce harmful gases, nor be harmful when touched.

► Application Method

It is important to use the proper amount of adhesive. Too little and much adhesive will cause poor adhesion and overflow into the land, respectively.

► Adhesive hardening Characteristics

To prevent oxidation of the terminations, the adhesive must harden at 160° C or less, within 2 minutes or less.

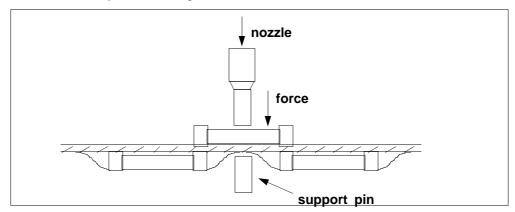
Mounting

► Mounting Head Pressure

Excessive pressure will cause crack to MLCCs. The pressure of nozzle will be 300g maximum during mounting.

▶ Bending Stress

When double-sided circuit boards are used, MLCCs first are mounted and soldered onto one side of the board. When the MLCCs are mounted onto the other side, it is important to support the board as shown in the illustration. If the circuit board is not supported, the crack occur to the ready-installed MLCCs by the bending stress.



Flux

Although the solderability increased by the highly-activated flux, increase of activity in flux may also degrade the insulation of the chip capacitors. To avoid such degradation, it is recommended that a mildly activated rosin flux(less than 0.2% chlorine) be used.

Soldering

Since a multilayer ceramic chip capacitor comes into direct contact with melted solder during soldering, it is exposed to potentially mechanical stress caused by the sudden temperature change. The capacitor may also be subject to silver migration, and to contamination by the flux. Because of these factors, soldering technique is critical.

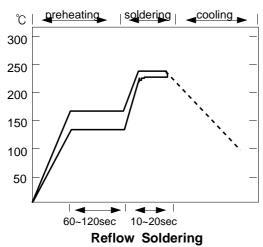
► Soldering Methods

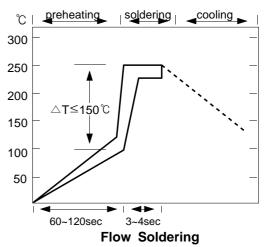
Method		Classification					
Reflow	- Overall heating	Infrared raysHot plateVPS(vapor phase)					
soldering	- Local heating	Air heaterLaserLight beam					
Flow soldering	- Single wave - Double wave	-					

^{*} We recommend the reflow soldering method.

▶ Soldering Profile

To avoid crack problem by sudden temperature change, follow the temperature profile in the adjacent graph.

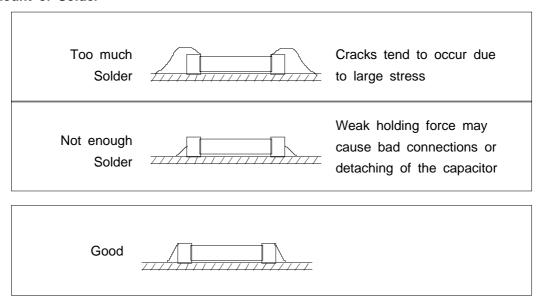




► Manual Soldering

Manual soldering can pose a great risk of creating thermal cracks in chip capacitors. The hot soldering iron tip comes into direct contact with the end terminations, and operator's carelessness may cause the tip of the soldering iron to come into direct contact with the ceramic body of the capacitor. Therefore the soldering iron must be handled carefully, and close attention must be paid to the selection of the soldering iron tip and to temperature control of the tip.

► Amount of Solder



▶ Cooling

Natural cooling using air is recommended. If the chips are dipped into solvent for cleaning, the temperature difference($\triangle T$) must be less than 100 $^{\circ}$ C

6-6. Cleaning

If rosin flux is used, cleaning usually is unnecessary. When strongly activated flux is used, chlorine in the flux may dissolve into some types of cleaning fluids, thereby affecting the chip capacitors. This means that the cleaning fluid must be carefully selected, and should always be new.

▶ Notes for Separating Multiple, Shared PC Boards.

A multi-PC board is separated into many individual circuit boards after soldering has been completed. If the board is bent or distorted at the time of separation, cracks may occur in the chip capacitors. Carefully choose a separation method that minimizes the bending of the circuit board.

■ CROSS REFERENCE

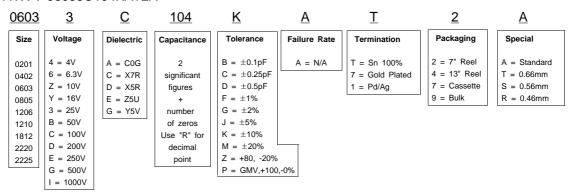
P/N	COMPANY	SAMSUNG	AVX	JOHANSON	KEMET	KYOCERA	MURATA	NOVACAP	PANASONIC	ROHM	TAIYO - YUDEN	TDK	VITRAMON
① COMPANY	MODEL(MLCC)	CL	-	-	С	СМ	GRM	-	ECJ	MCH	MK	С	۸٦
② SIZE (EIA/JIS)	0201(0603)	03	-	-	-	03	33	-	Z	-	063	0603	-
	0402(1005)	05	0402	R07	0402	05	36	0402	0	15	105	1005	0402
	0603(1608)	10	0603	R14	0603	105	39	0603	1	18	107	1608	0603
	0805(2012)	21	0805	R15	0805	21	40	0805	2	21	212	2012	0805
	1206(3216)	31	1206	R18	1206	316	42-6	1206	3	31	316	3216	1206
	1210(3225)	32	1210	S41	1210	32	42-2	1210	4	32	325	3225	1210
	1808(4520)	42	1808	R29	1808	42	=	1808	-	-	-	4520	1808
	1812(4532)	43	1812	S43	1812	43	43-2	1812	-	43	432	4532	1812
	2220(5750)	55	-	-	2220	55	44-1	2221	-	-	550	5650	-
	COG(NPO)	С	А	N	G	CG	COG/CH	N	С	Α	С	COG/CH	А
	P2H(N150)	P	s	-	-	Р	P2H	-	Р	-	Р	PH	-
	R2H(N220)	R	1	-	-	R	R2H	-	R	-	R	RH	-
	S2H(N330)	S	3	-	-	S	S2H	-	S	-	S	SH	-
3	T2H(N470)	Т	0	-	-	Т	T2H	-	Т	-	Т	TH	-
TEMPERATURE CHARACTERISTIC	U2J(N750)	U	Z	-	-	U	U2J	-	U	UJ	U	UJ	-
	S2L	L	Y	-	-	SL	SL	-	G	SL	SL	SL	-
	X7R	В	С	w	R(X)	X7R	X7R	В	В	С	BJ	X7R(B)	Y(X)
	Z5U	Е	Е	z	U	-	Z5U	Z	-	E	=	Z5U	U
	Y5V	F	G	Y	V	Y5V	Y5V	Y	F	F	F	Y5V	-
NOMINAL	CAPACITANCE			EX	() 103=10,0	00pF 221=	=220pF 225	5=2,200,000pF=2	2.2#F 1R5=1.5	5pF 010=1	pF		'
(5) CAPACITAN	CE TOLERANCE			B:±0.1pF C:	±0.25pF	D:±0.5pF F	F:±1% G:±	:2% J:±5%	K:±10%	M:±20%	Z:-20~+80%	•	
	6.3V	Q	6	-	9	06	6.3	-	0J	-	J	0.0	-
	10 V	Р	Z	100	8	10	10	-	1A	4	L	1A	-
	16 V	0	Υ	160	4	16	16	160	1C	3	E	1C	J
	25 V	А	3	250	3	25	25	250	1E	2	Т	1E	х
	50 V	В	5	500	5	50	50	500	1H	5	U	1H	А
	100 V	С	1	101	1	100	100	101	2A	1	=	2A	В
® RATED	200V	D	2	201	2	200	200	201	2D	=	=	-	С
VOLTAGE	250V	Е	V	-	-	250	250	251	-	-	-	2E	-
	500V	G	7	501	=	500	500	501	-	-	-	-	Е
	500V 630V	G H	7	501	-	500 630		501	-	-	-	- 2J	- E
							500						
	630V	н	-	-	-	630	500 630	-	-	-	-	2J	-
	630V 1000V	H	- A	102	-	630	500 630 1K	102	-	-	-	2J 3A	- G
	630V 1000V 2000V	H I J	- A G	102		630 1000 2000	500 630 1K 2K	102	-		-	2J 3A 3D	- G
(A) TEDUNIS	630V 1000V 2000V 3000V	H I J	A G H	102		630 1000 2000 3000	500 630 1K 2K 3K	- 102 202 302			-	2J 3A 3D 3F	- G
① TERMINATION	630V 1000V 2000V 3000V 4000V	H I J K	- A G H	- 102 202 302		630 1000 2000 3000 4000	500 630 1K 2K 3K	102 202 302 402	-		-	2J 3A 3D 3F	- G - H
TERMINATION	630V 1000V 2000V 3000V 4000V NICKEL BARRIER	H I J K - N	- A G H J T	- 102 202 302 V	- - - - - C	630 1000 2000 3000 4000 A	500 630 1K 2K 3K - (GRM)	- 102 202 302 402 N		- - - - (MCH)	-	2J 3A 3D 3F -	- G - H - X
	630V 1000V 2000V 3000V 4000V NICKEL BARRIER Ag/Pd	H I J K - N P	- A G H J T 1	- 102 202 302 V		630 1000 2000 3000 4000 A	500 630 1K 2K 3K - (GRM)	- 102 202 302 402 N		(MCH)	-	2J 3A 3D 3F -	- G - H - X
① TERMINATION ② PACKAGE	630V 1000V 2000V 3000V 4000V NICKEL BARRIER Ag/Pd BULK(VINYL)	H I J K - N P B	- A G H J T 1 9	- 102 202 302 V - (NONE)		630 1000 2000 3000 4000 A B	500 630 1K 2K 3K - (GRM) (GR) PB	- 102 202 302 402 N P	x	(MCH)	B	2J 3A 3D 3F - - B	- G - H - X F B



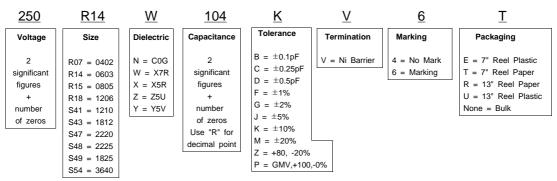
► SAMSUNG : CL10B104KA8NNNC

<u>CL</u>	<u>10</u>	<u>B</u>	<u>104</u>	<u>K</u>	<u>A</u>	<u>8</u>	<u>N</u>	<u>N</u>	<u>N</u>	<u>C</u>
Series	Size	Dielectric	Capacitance	Tolerance	Voltage	Thickness	Electrode/	Products	Special	Packaging
							Termination/			
	03 = 0201	C = C0G	2	$A = \pm 0.05pF$	Q = 6.3V	3 = 0.30	Plating	A = Array	Various	B = Bulk
	05 = 0402	P = P2H	significant	$B = \pm 0.1pF$	P = 10V	5 = 0.50		(2-element)		P = Cassette
	10 = 0603	R = R2H	figures	$C = \pm 0.25pF$	O = 16V	8 = 0.80	A = Pd/Ag/	B = Array		C = Paper 7"
	21 = 0805	S = S2H	+	$D = \pm 0.5pF$	A = 25V	A = 0.65	Sn 100%	(4-element)		D = Paper 13"
	31 = 1206	T = T2H	number	F = ±1%	B = 50V	C = 0.85	N = Ni/Cu/	C = High - Q		(10,000EA)
	32 = 1210	U = U2H	of zeros	$G = \pm 2\%$	C = 100V	H = 1.60	Sn 100%	L = LICC		E = Embossing 7"
	43 = 1812	L = S2L	Use "R" for	J = ±5%	D = 200V	I = 2.00	G = Cu/Cu/	N = Normal		F = Embossing 13"
	55 = 2220	B = X7R	decimal point	$K = \pm 10\%$	E = 250V	J = 2.50	Sn 100%	P = Automotive		L = Paper 13"
		A = X5R		$M = \pm 20\%$	G = 500V	L = 3.20		W = 3 terminal		(15,000EA)
		F = Y5V		Z = +80,-20%	H = 630V			chip		O = Paper 10"
					I = 1000V				_	S = Embossing 10"

► AVX: 06033C104KAT2A



▶ JOHANSON: 250R14W104KV6T



► KEMET: C0603C104K3RAC

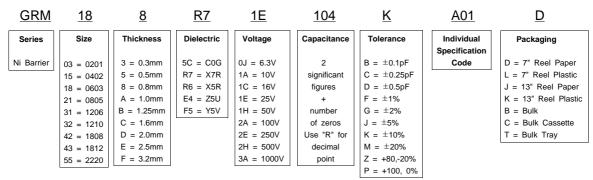
<u>C 0603 C 104 K 3 R</u>	<u>A</u> <u>C</u>
Series Size Specification Capacitance Tolerance Voltage Dielectric Failure	Rate Termination
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	O (Mil) H = Ni w/Solder T = Silver



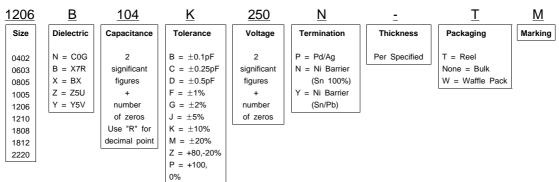
KYOCERA : CM105X7R104K25AT

<u>CM</u>	<u>105</u>	<u>X7R</u>	<u>104</u>	<u>K</u>	<u>25</u>	<u>A</u>	I
Series	Size	Dielectric	Capacitance	Tolerance	Voltage	Termination	Packaging
	03 = 0201 05 = 0402 105 = 0603 21 = 0805 316 = 1206 32 = 1210 42 = 1808 43 = 1812 55 = 2220	CG X8R X7R X5R Z5U Y5V Y5U	2 significant figures + number of zeros Use "R" for decimal point	$B = \pm 0.1pF$ $C = \pm 0.25pF$ $D = \pm 0.5pF$ $F = \pm 1\%$ $G = \pm 2\%$ $J = \pm 5\%$ $K = \pm 10\%$ $M = \pm 20\%$ $Z = +80, -20\%$ $P = +100, 0\%$	04 = 4V 06 = 6.3V 10 = 10V 16 = 16V 25 = 25V 50 = 50V 100 = 100V 250 = 250V 500 = 500V 1000 = 1000V	A = Ni Barrier	T = 7" Reel (4mm Pitch) L = 13" Reel (4mm Pitch) H = 7" Reel (2mm Pitch) N = 13" Reel (2mm Pitch) B = Bulk (Vinyl Bags) C = Bulk Cassette

► MURATA: GRM188R71E104KA01D



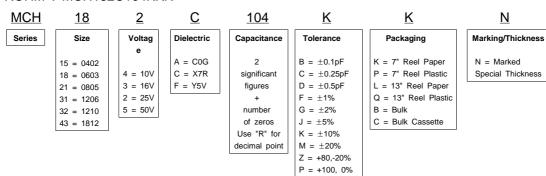
► NOVACAP: 0603B104K250N_TM



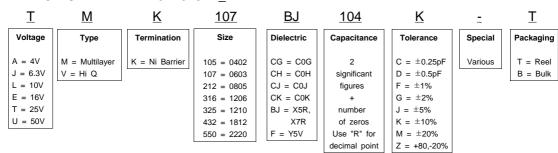
► PANASONIC : ECJ1EB1E104K

<u>ECJ</u>	<u>1</u>	<u>E</u>	<u>B</u>	<u>1E</u>	<u>104</u>	<u>K</u>
Series	Size	Packaging	Dielectric	Voltage	Capacitance	Tolerance
	Z = 0201 0 = 0402 1 = 0603 2 = 0805 3 = 1206 4 = 1210	X = Bulk E = Paper 2mm V = Paper 4mm F, Y = Plastic 4mm W = Large Reels 2mm Z = Large Reels 4mm C = Bulk Cassette	C = C0G B = X7R, X5R F = Y5V	0J = 6.3V 1A = 10V 1C = 16V 1E = 25V 1H = 50V 2A = 100V 2D = 200V	2 significant figures + number of zeros Use "R" for	$C = \pm 0.25pF$ $D = \pm 0.5pF$ $F = \pm 1\%$ $J = \pm 5\%$ $K = \pm 10\%$ $M = \pm 20\%$ $Z = +80, -20\%$
					decimal point	

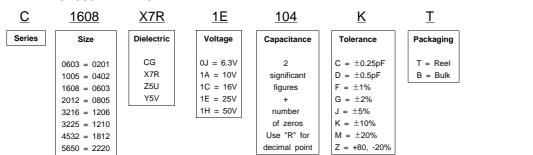
► ROHM: MCH182C104KKN



► TAIYO-YUDEN: TMK107BJ104K_T



► TDK: C1608X7R1E104KT



► VITRAMON: VJ0603Y104KXXMC

VIIIVA	IVIOIN	. ٧٥٥٥٥٥١	TOTICALINIC	,				
<u>VJ</u>	<u>0603</u>	<u>Y</u>	<u>104</u>	<u>K</u>	X	<u>X</u>	<u>M</u>	<u>C</u>
Series	Size	Dielectric	Capacitance	Tolerance	Termination	Voltage	Marking	Packaging
	0402 0603 0805 1206 1210 1812 2225	X = BX A,N = C0G Y = X7R U = Z5U H = X8R	2 significant figures + number of zeros Use "R" for decimal point	$B = \pm 0.1 pF$ $C = \pm 0.25 pF$ $D = \pm 0.5 pF$ $F = \pm 1\%$ $G = \pm 2\%$ $J = \pm 5\%$ $K = \pm 10\%$ $M = \pm 20\%$ $Z = +80, -20\%$ $P = +100, 0\%$	X = Silver, Ni Barrier Tin Plated	J = 16V X = 25V A = 50V B = 100V C = 200V	M = Marking A = No Marking	C = 7" Reel Paper T = 7" Reel Plastic P = 13" Reel Paper R = 13" Reel Plastic B = Bulk